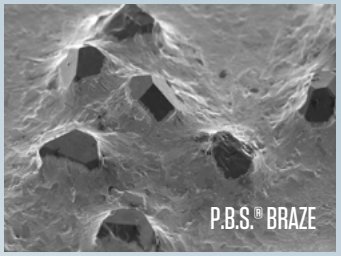
CMP CONDITIONING DISKS

As the pioneer in P.B.S.® brazed bonding for CMP pad conditioning disks, Abrasive Technology has set the industry standards for performance, consistency and efficiency.

abrasive technology
www.abrasive-tech.com
800.964.8324

FEATURES

- Operate on all major CMP equipment platforms in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu) processes.
- Specialized manufacturing technology to control critical abrasive specifications (diamond size, shape, bond height, diamond plane), which delivers high performance.
- Ideal for both in-situ and ex-situ CMP processes to meet critical CMP process requirements.
- Available in magnetic and non-magnetic grades of stainless steel in variety of front surface configurations and sizes.



THE P.B.S.® ADVANTAGE

- Individually and permanently brazes diamonds in place, increasing crystal retention.
- Greater control over crystal concentration, creating a more consistent pad surface.
- Chemical bond is more durable than electroplated and protects the crystals, extending the life of each disk.

CMP DISK FOR COPPER

Abrasive Technology's P.B.S.® brazed disks for CMP pad conditioning are precisely manufactured for the highest productivity in semiconductor wafer processing. Our disks are customized to operate on Oxide, Tungsten and Copper processes.

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Performance:
Third party testing confirmed consistent, high-performance results on AT disks when compared to the leading competitor.

Value:
Users achieve lower cost of ownership with AT disk:

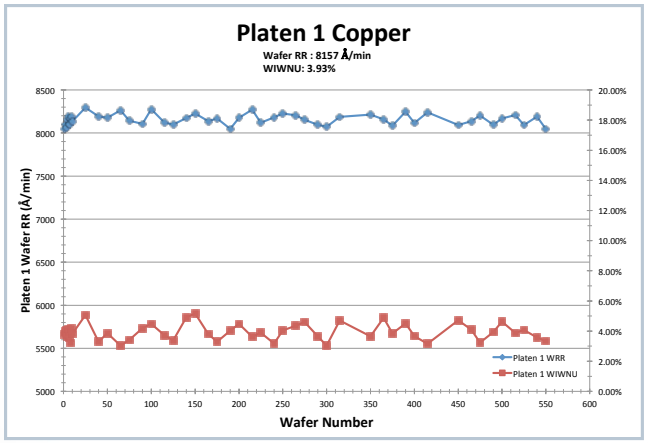
- Improve price
- Higher quality
- Consistent performance

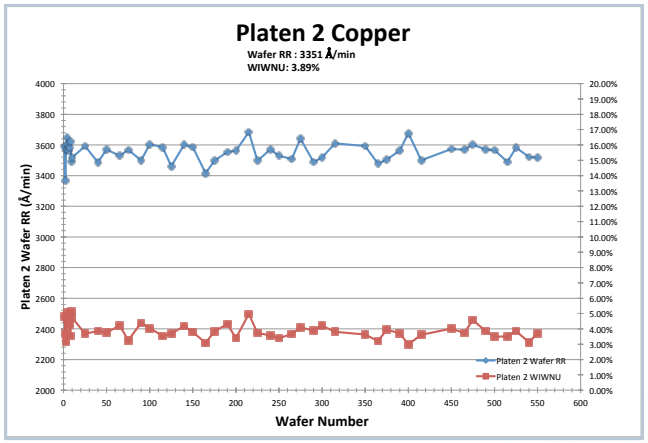
Customer Data: Copper Process

Polishing Tool: *EP0012-T/300mm AiGIISHead*

Polish Pad: *IC1000K/SubaIV*

Slurry: *Cabot*





*Data collected from customer ran on unoptimized process with conditioner.